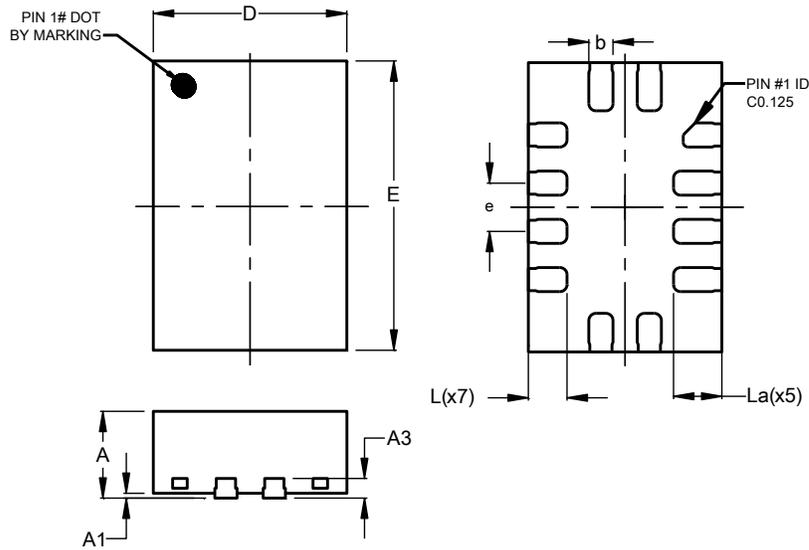


## Package Outline Dimensions

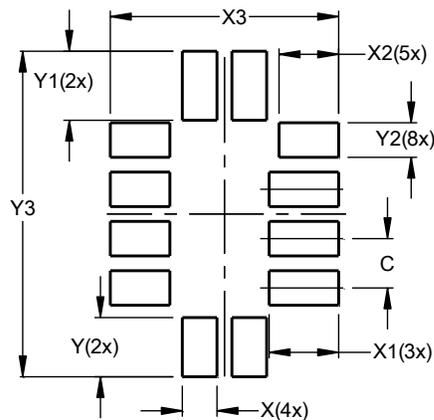
W-QFN2030-12



W-QFN2030-12			
Dim	Min	Max	Typ
A	0.700	0.800	0.750
A1	--	0.050	--
A3	0.203 REF		
b	0.200	0.300	0.250
D	1.950	2.050	2.000
E	2.950	3.050	3.000
e	0.500 BSC		
L	0.350	0.450	0.400
La	0.450	0.550	0.50
All Dimensions in mm			

## Suggested Pad Layout

W-QFN2030-12



Dimensions	Value (in mm)
C	0.500
X	0.350
X1	0.700
X2	0.600
X3	2.300
Y	0.600
Y1	0.700
Y2	0.350
Y3	3.300

### ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.